

TECHNICAL DATA SHEET

SLIDE®

KLENZ
Purging Compound

KLENZ Purging Compound 468-45, 468-1000

Product Description

KLENZ is a revolutionary purging compound requiring no mixing or preparation time. With operating temperatures of 330° - 610°F, KLENZ thoroughly cleanses hot runners and the barrel, helping to eliminate color streaking and black specks. Formulated with a polyolefin resin carrier, KLENZ purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for food packaging applications. For use with injection molding, extrusion and blow molding.

Applications	Purging Compound
Unit Package Description	48 and 1,100 pound boxes
Generic Description	Purging Compound
Net Weight Fill	45 & 1,000 pounds
UPC Code	858799000684
Appearance	Resin Pellet
Odor	None
Flash Point F	>750 degrees
Flash Point C	>400 degrees
Base Type	Resin
Evaporation Rate	N/A
HMIS Rating	0, 0, 0, None
DOT Proper Shipping Name	Not regulated, Granules, NOI
Removal	N/A
Units Per Case	45 & 1,000 pounds
Case Weight (lbs)	45 / 1,000
Working Temperature F	330 to 610 degrees
Working Temperature C	165 to 321 degrees
Propellant	N/A
NFPA Aerosol Flammability Level	N/A

